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SEMICONDUCTOR®

IGBT

FGL60N100BNTD

NPT-Trench IGBT

General Description

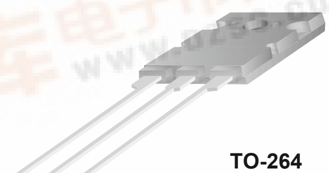
Trench insulated gate bipolar transistors (IGBTs) with NPT technology show outstanding performance in conduction and switching characteristics as well as enhanced avalanche ruggedness. These devices are well suited for Induction Heating (I-H) applications

Features

- High Speed Switching
- Low Saturation Voltage : $V_{CE(sat)}$ = 2.5 V @ I_C = 60A
- High Input Impedance
- Built-in Fast Recovery Diode

Application

Micro- Wave Oven, I-H Cooker, I-H Jar, Induction Heater, Home Appliance



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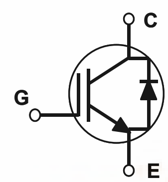

Absolute Maximum Ratings

T_C = 25°C unless otherwise noted

Symbol	Description		FGL60N100BNTD	Units
V_{CES}	Collector-Emitter Voltage		1000	V
V_{GES}	Gate-Emitter Voltage		± 25	V
I_C	Collector Current	@ T_C = 25°C	60	A
	Collector Current	@ T_C = 100°C	42	A
$I_{CM\ (1)}$	Pulsed Collector Current		120	A
I_F	Diode Continuous Forward Current	@ T_C = 100°C	15	A
P_D	Maximum Power Dissipation	@ T_C = 25°C	180	W
	Maximum Power Dissipation	@ T_C = 100°C	72	W
T_J	Operating Junction Temperature		-55 to +150	°C
T_{stg}	Storage Temperature Range		-55 to +150	°C
T_L	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes :
(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$(IGBT)	Thermal Resistance, Junction-to-Case	--	0.69	°C/W
$R_{\theta JC}$(DIODE)	Thermal Resistance, Junction-to-Case	--	2.08	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	25	°C/W

Electrical Characteristics of IGBT
T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Off Characteristics						
BV_{CES}	Collector Emitter Breakdown Voltage	V_{GE} = 0V, I_C = 1mA	1000	--	--	V
I_{CES}	Collector Cut-Off Current	V_{CE} = 1000V, V_{GE} = 0V	--	--	1.0	mA
I_{GES}	G-E Leakage Current	V_{GE} = ± 25, V_{CE} = 0V	--	--	± 500	nA
On Characteristics						
$V_{GE(th)}$	G-E Threshold Voltage	I_C = 60mA, V_{CE} = V_{GE}	4.0	5.0	7.0	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	I_C = 10A, V_{GE} = 15V	--	1.5	1.8	V
		I_C = 60A, V_{GE} = 15V	--	2.5	2.9	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	V_{CE}=10V, V_{GE} = 0V, f = 1MHz	--	6000	--	pF
C_{oes}	Output Capacitance		--	260	--	pF
C_{res}	Reverse Transfer Capacitance		--	200	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{CC} = 600 V, I_C = 60A, R_G = 51Ω, V_{GE}=15V, Resistive Load, T_C = 25°C	--	140	--	ns
t_r	Rise Time		--	320	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	630	--	ns
t_f	Fall Time		--	130	250	ns
Q_g	Total Gate Charge	V_{CE} = 600 V, I_C = 60A, V_{GE} = 15V , , T_C = 25°C	--	275	350	nC
Q_{ge}	Gate-Emitter Charge		--	45	--	nC
Q_{gc}	Gate-Collector Charge		--	95	--	nC

Electrical Characteristics of DIODE
T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{FM}	Diode Forward Voltage	I_F = 15A	--	1.2	1.7	V
		I_F = 60A	--	1.8	2.1	V
t_{rr}	Diode Reverse Recovery Time	I_F = 60A di/dt = 20 A/us		1.2	1.5	us
I_R	Instantaneous Reverse Current	V_{RRM} = 1000V	--	0.05	2	uA

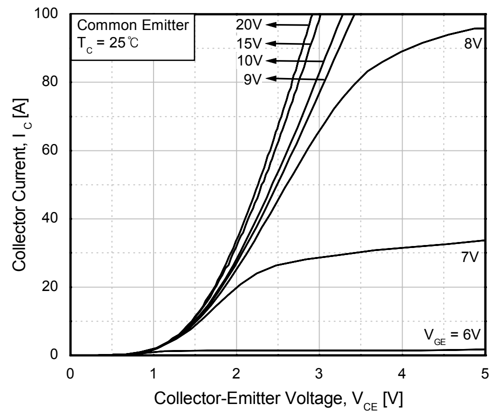

Fig 1. Typical Output Characteristics

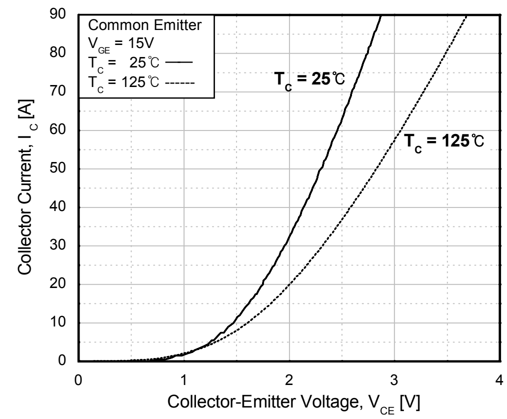

Fig 2. Typical Saturation Voltage Characteristics

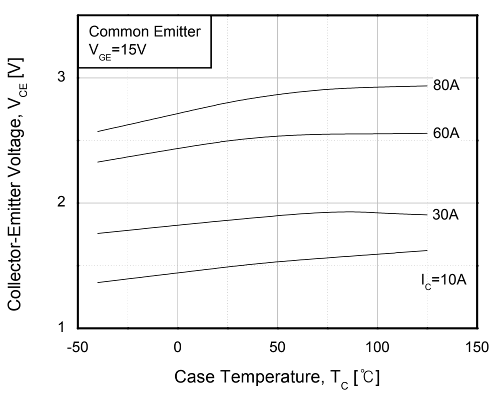

Fig 3. Saturation Voltage vs. Case Temperature at Varient Current Level

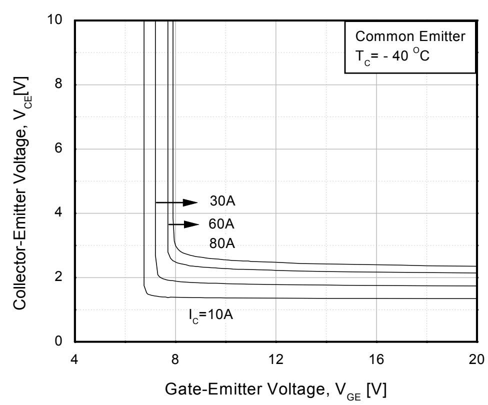

Fig 4. Saturation Voltage vs. V_{GE}

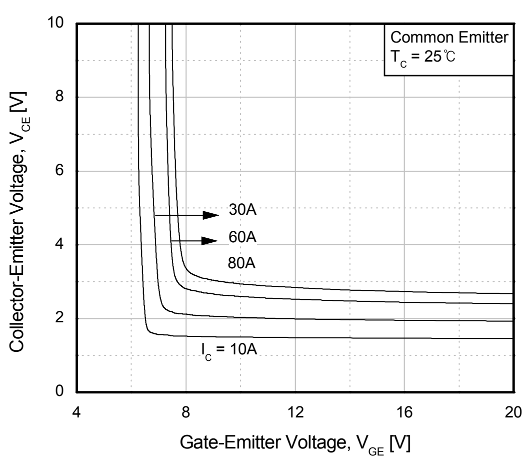

Fig 5. Saturation Voltage vs. V_{GE}

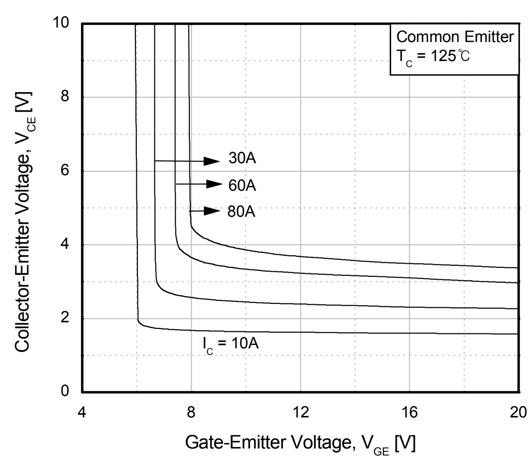

Fig 6. Saturation Voltage vs. V_{GE}

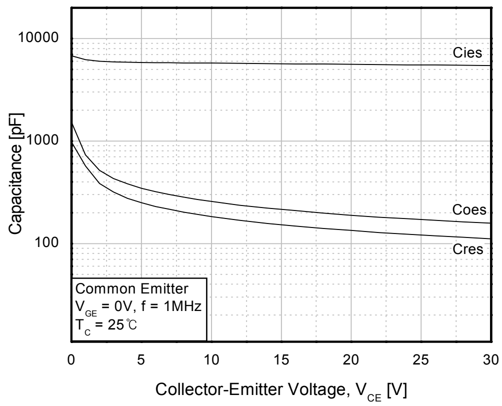

Fig 7. Capacitance Characteristics

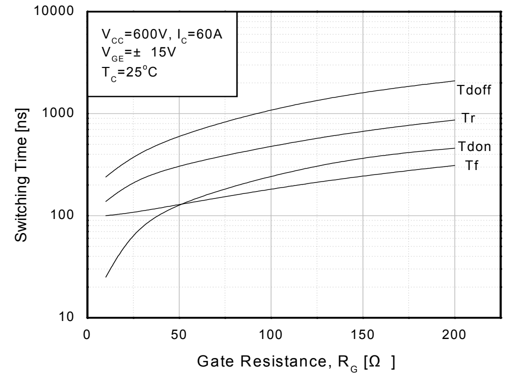

Fig 8. Switching Characteristics vs. Gate Resistance

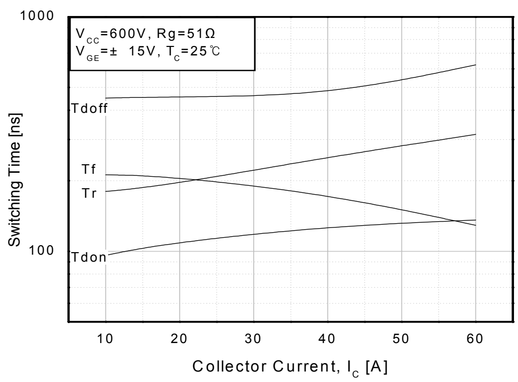

Fig 9. Switching Characteristics vs. Collector Current

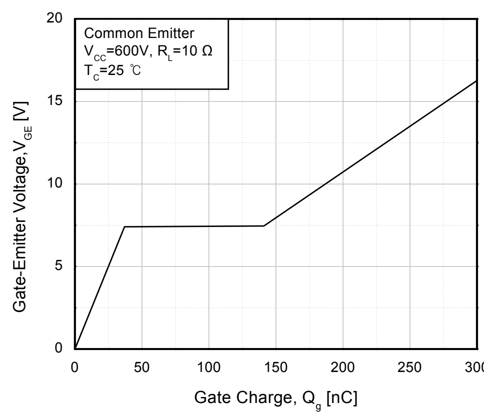

Fig 10. Gate Charge Characteristics

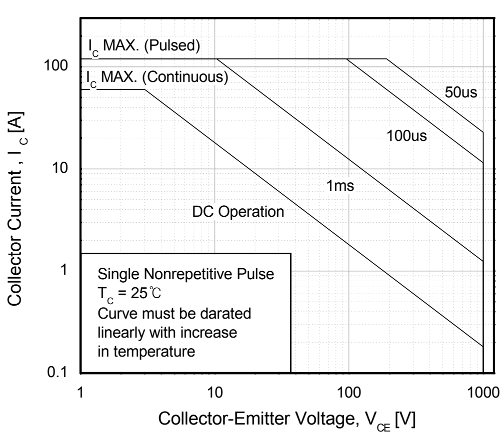

Fig 11. SOA Characteristics

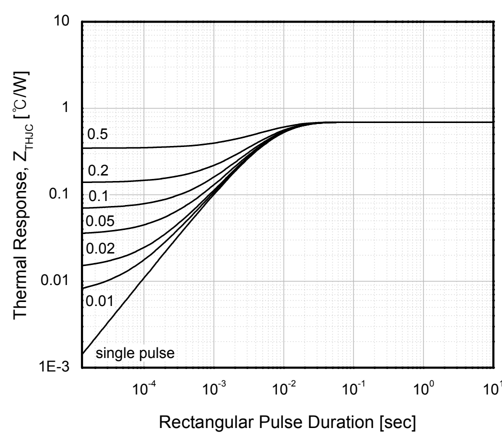

Fig 12. Transient Thermal Impedance of IGBT

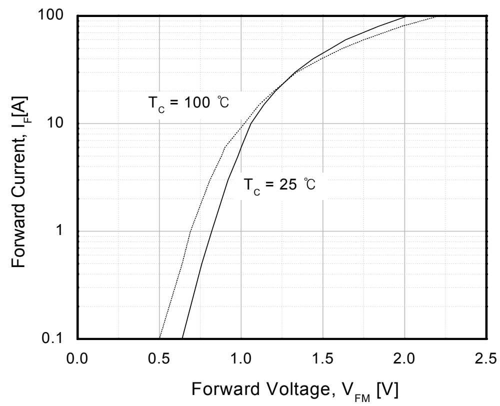

Fig 13. Forward Characteristics

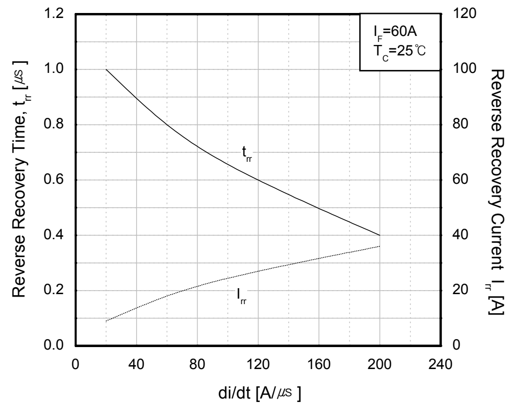

Fig 14. Reverse Recovery Characteristics vs. di/dt

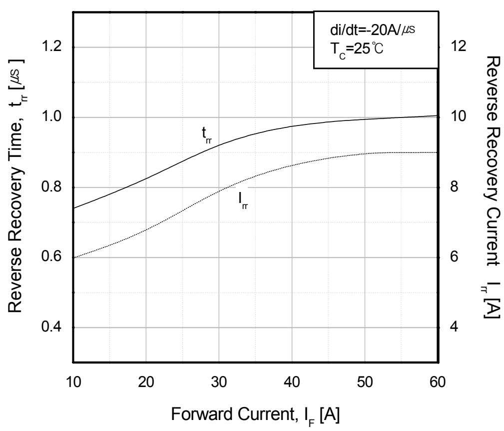

Fig 15. Reverse Recovery Characteristics vs. Forward Current

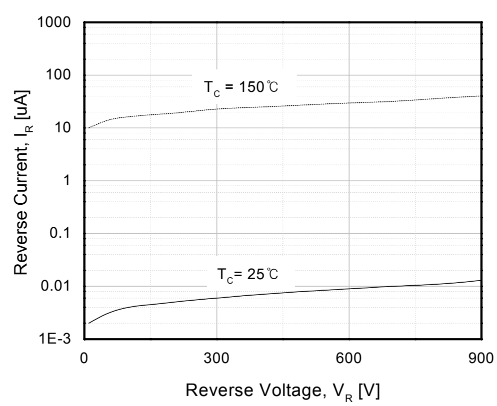

Fig 16. Reverse Current vs. Reverse Voltage

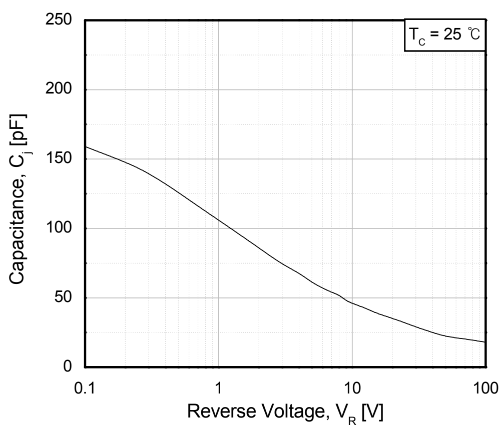

Fig 17. Junction capacitance

Package Dimension

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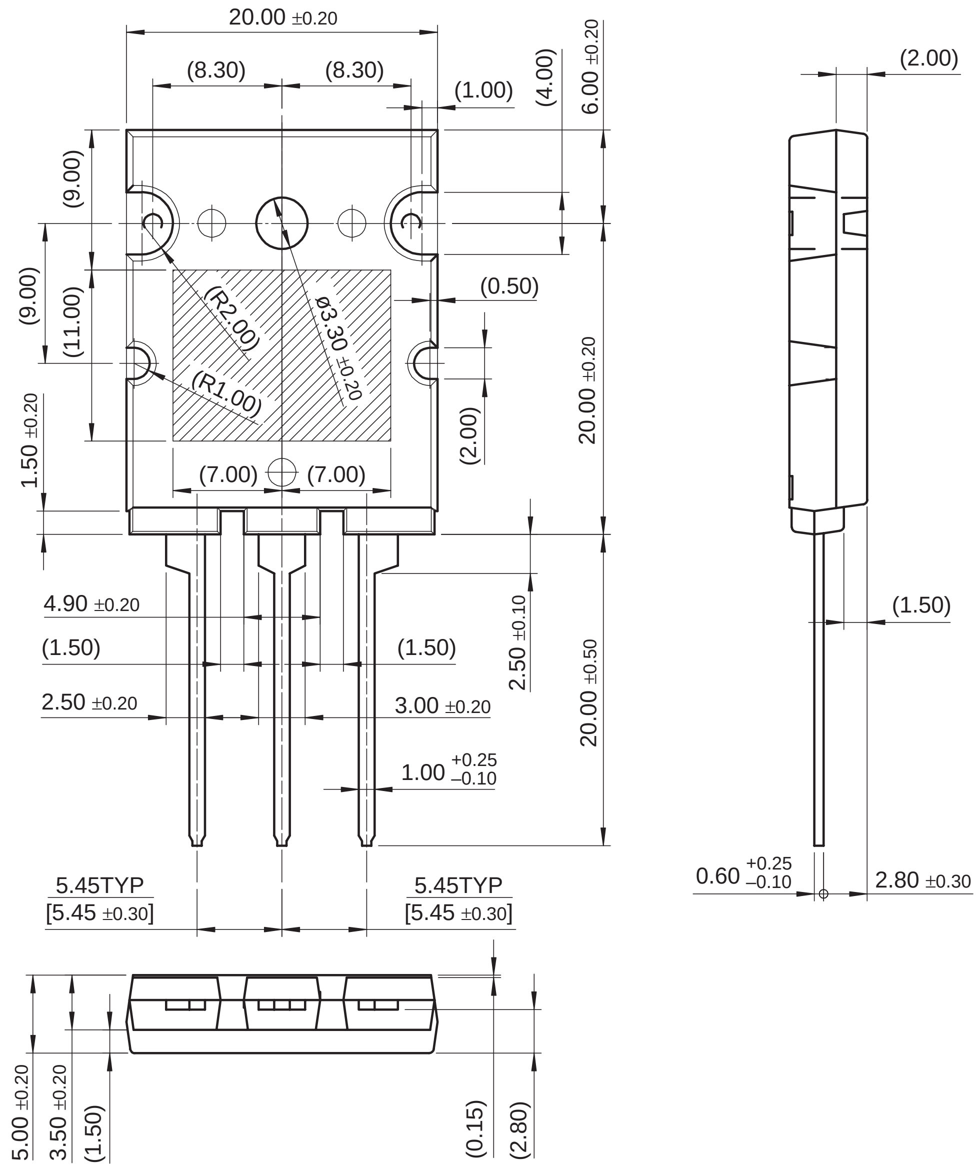

Dimensions in Millimeters

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